# Sil-Pad® 900S

# High Performance Insulator for Low-Pressure Applications

#### **Features and Benefits**

- Thermal impedance: 0.61°C-in²/W (@50 psi)
- Electrically isolating
- Low mounting pressures
- Smooth and highly compliant surface
- General-purpose thermal interface material solution



The true workhorse of the Sil-Pad product family, Sil-Pad 900S thermally conductive insulation material is designed for a wide variety of applications requiring high thermal performance and electrical isolation. These applications also typically have low mounting pressures for component clamping.

Sil-Pad 900S material combines a smooth and highly compliant surface characteristic with high thermal conductivity. These features optimize the thermal resistance properties at low pressures.

Applications requiring low component clamping forces include discrete semiconductors (TO-220, TO-247 and TO-218) mounted with spring clips. Spring clips assist with quick assembly and apply a limited amount of force to the semiconductor. The smooth surface texture of Sil-Pad 900S minimizes interfacial thermal resistance and maximizes thermal performance.

TYPICAL PROPERTIES OF SIL-PAD 900S						
PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	Pink		Pink		Visual	
Reinforcement Carrier	Fiberglass		Fiberglass		_	
Thickness (inch) / (mm)	0.009		0.229		ASTM D374	
Hardness (Shore A)	92		92		ASTM D2240	
Elongation (%45° to Warp and Fill)	20		20		ASTM D412	
Tensile Strength (psi) / (MPa)	1300		9		ASTM D412	
Continuous Use Temp (°F) / (°C)	-76 to 356		-60 to 180		_	
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)	5500		5500		ASTM D149	
Type 3 Electrodes	8300		8300		ASTM D149	
Dielectric Constant (1000 Hz)	6.0		6.0		ASTM D150	
Volume Resistivity (Ohm-meter)	10 <sup>10</sup>		10 <sup>10</sup>		ASTM D257	
Flame Rating	V-O		V-O		U.L. 94	
THERMAL						
Thermal Conductivity (W/m-K)	1.6		1.6		ASTM D5470	
THERMAL PERFORMANCE vs PRESS	URE					
Press	sure (psi)	10	25	50	100	200
TO-220 Thermal Performance	e (°C/W)	3.96	3.41	2.90	2.53	2.32
Thermal Impedance (°C-ir	Thermal Impedance (°C-in²/W) (1)		0.75	0.61	0.47	0.41
1) The ASTM D5470 test fixture was used. The recor	ded value inclu	ides interfacia	I thermal resis	tance. These v	alues are prov	ided for

reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

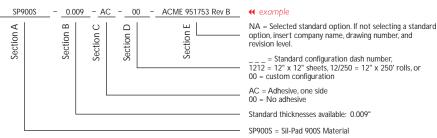
### **Typical Applications Include:**

- Power supplies
- Automotive electronics
- Motor controls
- Power semiconductors

# **Configurations Available:**

- Sheet form, die-cut parts, and roll form
- With or without pressure sensitive adhesive

# **Building a Part Number**



Note: To build a part number, visit our website at www.bergquistcompany.com.

Sil-Pad °: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others

**Standard Options**